



100% Material Declaration Data Sheet FGG256

PK105 (v1.1) June 29, 2006

Material Declaration Data Sheet

Average Weight: 0.9408 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.0749	7.97%
	Silicon	7440-21-3	100.00		0.0749	
Die Attach Material		2300		Silver paste die attach material	0.0074	0.78%
	Silver	7440-22-4	78.00		0.0058	
	Resin	Trade Secret	22.00		0.0016	
Mold Compound		EME G770			0.3748	39.84%
	Epoxy Resins	Trade Secret	12.00		0.0450	
	SiO2	60676-86-0	88.00	Filler	0.3298	
Laminate		CCL-HL832 (BT)			0.2085	22.16%
	Laminate	Trade Secret	61.00		0.1272	
	Solder Mask	Trade Secret	17.36		0.0362	
	Copper	7440-50-8	16.00	Metal Layer	0.0334	
	Nickel	7440-02-0	4.80	Metal Layer	0.0100	
	Gold	7440-57-5	0.84	Metal Layer	0.0018	
Bond Wire		MKE HTS-Type		Bonding die to package	0.0043	0.46%
	Gold	7440-57-5	99.00		0.004263581	
	Silver	7440-22-4	0.0025		0.000000108	
	Copper	7440-50-8	0.0005		0.000000022	
	Iron	7439-89-6	0.0005		0.000000022	
	Calcium	7440-70-2	0.0020		0.000000086	
	Palladium	7440-05-3	0.9900		0.000042636	
	Magnesium	7439-95-4	0.0005		0.000000022	
Solder Balls					0.2709	28.79%
	Tin	7440-31-5	95.50		0.2587	
	Silver	7440-22-4	4.00		0.0108	
	Copper	7440-50-8	0.50		0.0014	

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1

Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/21/06	1.0	Initial release.
6/29/06	1.1	100% Material Declaration.